

Product/Process Change Notice - PCN 16_0062 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Aerospace AD8351S Change of Wire Diameter

Publication Date: 23-Mar-2016

Effectivity Date: 21-Apr-2016 (the earliest date that a customer could expect to receive changed material)

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Revision	Description:
1 40 4131011	Description.

Initial Release		

Description Of Change

The Aluminum bonding wire for device AD8351S will be changed from 1.25 mils to 1 mil. The 1 mil Aluminum wire has been previously qualified on other Aerospace devices/products.

Reason For Change

Improve the wire bonding process for 3×3 bond pad opening.

Impact of the change (positive or negative) on fit, form, function & reliability

No effect on fit, function and reliability.

Product Identification (this section will describe how to identify the changed material)

Date code 1528A

Summary of Supporting Information

Qualification will be performed per MIL-PRF-38535, Group B, C and D testing. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_16_0062_Rev_-_AD8351 Qualification Plan.pdf

For questions on this PCN.	please send an email to the red	gional contacts below or contact v	your local ADI sales representatives.

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (3)				
AD8351S / 5962L0821802V2A	AD8351S / 5962R0821801V2A	AD8351S / AD8351ARC-EMX		

Appendix B - Revision History			
Rev	Publish Date	Effectivity Date	Rev Description
Rev	23-Mar-2016	21-Apr-2016	Initial Release

Analog Devices, Inc.

DocId:3642 Parent DocId:None Layout Rev:7